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Dimensions	
Chip Size	1206
L	3.2mm +0.3/-0.25mm (0.126 in +0.012/-0.01 in)
W	1.6mm +0.3/-0.25mm (0.063 in +0.012/-0.01 in)
T	1.8mm MAX (0.071 in MAX)
B	0.51mm +/-0.36mm (0.02 in +/-0.014 in)

Packaging Specifications	
Packaging	Waffle
Packaging Quantity	126

General Information	
Series	SMD MIL BP PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	Yes
Termination	Gold
Failure Rate	N/A
Qualifications	MIL-PRF-32535 T-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.027 uF
Capacitance Tolerance	10%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Dissipation Factor	0.25% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	37.04 GOhms

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